

Master Bond EP21TPND Non Drip Polysulfide Based Two Component Adhesive System

Category: Polymer, Adhesive, Thermoset, Epoxy, Epoxy Adhesive

Material Notes:

Master Bond Polymer Adhesive EP21TPND is a two component polysulfide/epoxy based adhesive/sealant formulated to cure at room temperature or more rapidly at elevated temperatures, with a 100 to 100 mix ratio (A/B) by weight. It readily develops a high bonding strength of more than 1000 psi at room temperature which unlike that of many other epoxy adhesives, is relatively insensitive to mixing ratio or substrate cleaning procedures. EP21TPND can be applied without sagging or dripping even on vertical surfaces.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Master-Bond-EP21TPND-Non-Drip-Polysulfide-Based-Two-Component-Adhesive-System.php

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	121 °C	250 °F	
Minimum Service Temperature, Air	-51.1 °C	-60.0 °F	

Processing Properties	Metric	English	Comments
Cure Time	60.0 - 120 min	1.00 - 2.00 hour	
	@Temperature 93.3 °C	@Temperature 200 °F	
	2880 - 3600 min	48.0 - 60.0 hour	
	@Temperature 23.0 °C	@Temperature 73.4 °F	

Descriptive Properties	Value	Comments
Color Code	"A" Black; "B" Tan	
Mix Ratio By Weight	100/100	
Set-Up Time, minutes	30-45	At Room Temperature
Viscosity	Thixotropic Paste	Room Temperature

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